

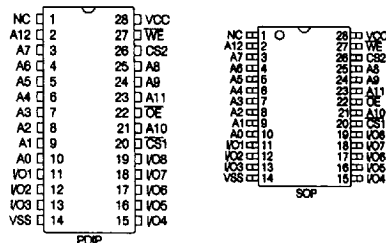
DESCRIPTION

The HY6264A-I is a high-speed, low power and 8,192 x 8-bits CMOS static RAM fabricated using Hyundai's high performance twin tub CMOS process technology. This high reliability process coupled with innovative circuit design techniques, yields maximum access time of 70ns. The HY6264A-I has a data retention mode that guarantees data to remain valid at a minimum power supply voltage of 2.0 volt. Using CMOS technology, supply voltages from 2.0 to 5.5 volt have little effect on supply current in data retention mode. Reducing the supply voltage to minimize current drain is unnecessary with the HY6264A-I Series. -40°C to 85°C operating temperature range is suitable for industrial use.

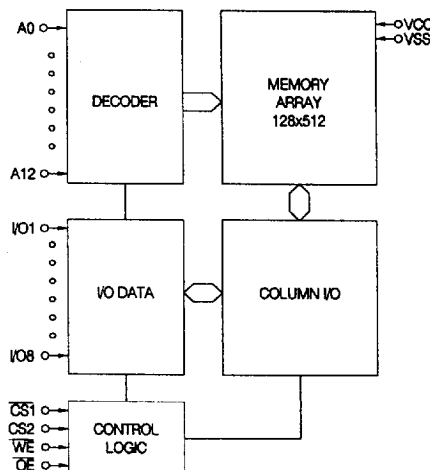
FEATURES

- Extended temperature range : -40°C to 85°C
- High speed-70/85/100/120ns (max.)
- Low power consumption
 - Operating : 150mW (typ.)
 - Standby (CMOS) : 10μW (typ.)
- Single 5V±10% power supply
- Battery backup(L/LL-part)
 - 2.0V (min.) data retention
- Fully static operation
 - No clock or refresh required
- TTL compatible inputs and outputs
- Tri-state output
- Standard pin configuration
 - 28 pin 600 mil PDIP
 - 28 pin 330 mil SOP

PIN CONNECTION



BLOCK DIAGRAM



PIN DESCRIPTION

Pin Name	Pin Function
CS1	Chip Select 1
CS2	Chip Select 2
WE	Write Enable
OE	Output Enable
A0-A12	Address Inputs
I/O1-I/O8	Data Input/Output
Vcc	Power(+5V)
Vss	Ground
NC	No Connect

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

SYMBOL	PARAMETER	RATING	UNIT
VCC, VIN, VOUT	Power Supply, Input/Output Voltage	-0.5 to 7.0	V
TA	Operating Temperature	-40 to 85	°C
TBIAS	Temperature Under Bias	-10 to 125	°C
TSTG	Storage Temperature	-65 to 150	°C
PD	Power Dissipation	1.0	W
IOUT	Data Output Current	50	mA
TSOLDER	Lead Soldering Temperature & Time	260 • 10	°C • sec

NOTE:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational of this specification is not implied. Exposure to absolute maximum rating conditions for extended period may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

(TA = -40°C to 85°C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VCC	Power Supply Voltage	4.5	5.0	5.5	V
VIH	Input High Voltage	2.2	-	Vcc+0.5	V
VIL	Input Low Voltage	-0.5 ⁽¹⁾	-	0.8	V

NOTE:

- VIL = -3.0V for pulse width less than 50ns

TRUTH TABLE

MODE	IO OPERATION	CS1	CS2	WE	OE
Standby	High-Z	H	X	X	X
	High-Z	X	L	X	X
Output Disabled	High-Z	L	H	H	H
Read	Data out	L	H	H	L
Write	Data in	L	H	L	X

NOTE:

- H=VIH, L=VIL, X=Don't Care

DC CHARACTERISTICS

(TA = -40°C to 85°C, VCC = 5V± 10%, unless otherwise specified.)

SYMBOL	PARAMETER	TEST CONDITIONS	POWER	MIN.	TYP.	MAX.	UNIT
ILI	Input Leakage Current	$V_{SS} \leq V_{IN} \leq V_{CC}$		-1	-	1	μA
ILO	Output Leakage Current	$V_{SS} \leq V_{OUT} \leq V_{CC}$ $\overline{CS1} = V_{IH}$ or $CS2 = V_{IL}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$		-1	-	1	μA
ICC	Operating Power Supply Current	$\overline{CS1} = V_{IL}$, $CS2 = V_{IH}$, $V_{IN} = V_{IH}$ or V_{IL} , $I_{I/O} = 0mA$		-	30	50	mA
ICC1	Average Operating Current	$\overline{CS1} = V_{IL}$, $CS2 = V_{IH}$ Min. Duty Cycle=100%, $I_{I/O} = 0mA$		-	30	50	mA
ISB	TTL Standby Current (TTL Inputs)	$\overline{CS1} = V_{IH}$ or $CS2 = V_{IL}$		-	0.4	2	mA
ISB1	CMOS Standby Current (CMOS Inputs)	$\overline{CS1} \geq V_{CC} - 0.2$, $CS2 \leq 0.2V$, or $CS2 \geq V_{CC} - 0.2V$	L	-	2	100	μA
			LL	-	1	30	μA
VOL	Output Low Voltage	$I_{OL} = 2.1mA$		-	-	0.4	V
VOH	Output High Voltage	$I_{OH} = -1.0mA$		2.4	-	-	V

NOTE:

1. Typical values are at VCC=5.0V, TA=25°C

AC CHARACTERISTICS

(TA=-40°C to 85°C, VCC=5V ±10%, unless otherwise noted.)

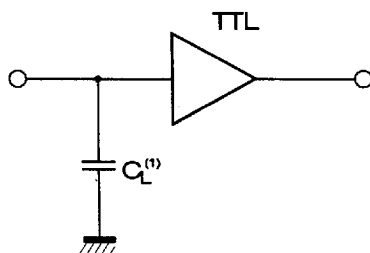
#	SYMBOL	PARAMETER	-70		-85		-10		-12		UNIT
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
READ CYCLE											
1	tRC	Read Cycle Time	70	-	85	-	100	-	120	-	ns
2	tAA	Address Access Time	-	70	-	85	-	100	-	120	ns
3	tACS	Chip Select Access Time	-	70	-	85	-	100	-	120	ns
4	tOE	Output Enable to Output Valid	-	45	-	50	-	55	-	60	ns
5	tCLZ	Chip Select to Low -Z Output	10	-	10	-	10	-	15	-	ns
6	tOLZ	Output Enable to Low-Z Output	5	-	5	-	5	-	5	-	ns
7	tCHZ	Chip Disable to High -Z Output	0	30	0	35	0	35	0	40	ns
8	tOHZ	Output Disable to High -Z Output	0	30	0	35	0	35	0	40	ns
9	tOH	Output Hold from Address Change	5	-	5	-	10	-	10	-	ns
WRITE CYCLE											
10	tWC	Write Cycle Time	70	-	85	-	100	-	120	-	ns
11	tCW	Chip Select to End of Write	55	-	60	-	70	-	85	-	ns
12	tAW	Address Valid to End of Write	55	-	60	-	70	-	85	-	ns
13	tAS	Address Set-up Time	0	-	0	-	0	-	0	-	ns
14	tWP	Write Pluse Width	50	-	55	-	60	-	70	-	ns
15	tWR	Write Recovery Time	0	-	0	-	0	-	0	-	ns
16	tWHZ	Write to High-Z Output	0	30	0	35	0	35	0	40	ns
17	tDW	Data to Write Time Overlap	35	-	35	-	40	-	50	-	ns
18	tDH	Data Hold from Write Time	0	-	0	-	0	-	0	-	ns
19	tOW	Output Active from End of Write	5	-	5	-	5	-	5	-	ns

AC TEST CONDITIONS

(TA=-40°C to 85°C, VCC=5V ± 10%, unless otherwise specified.)

PARAMETER	VALUE
Input Pulse Level	0.8V to 2.4V
Input Rise and Fall Time	5ns
Input and Output Timing Reference levels	1.5V
Output Load	CL=100pF + 1TTL Load

AC TEST LOADS



NOTE:

1. Including jig and scope capacitance.

CAPACITANCE

(TA=25°C, f= 1MHz)

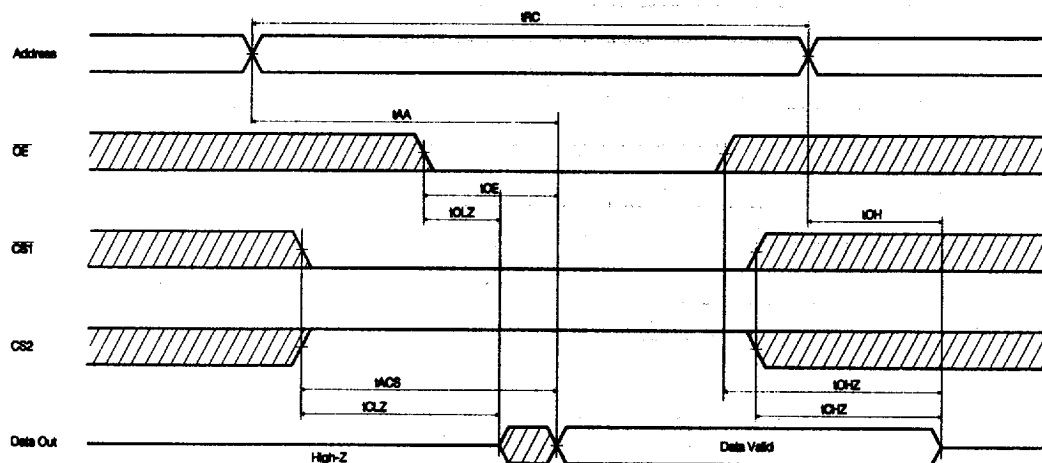
SYMBOL	PARAMETER	CONDITION	MAX.	UNIT
CIN	Input Capacitance	VIN=0V	6	pF
CIO	Input/Output Capacitance	VIO=0V	8	pF

Note:

1. This parameter is sampled and not 100% tested.

TIMING DIAGRAM

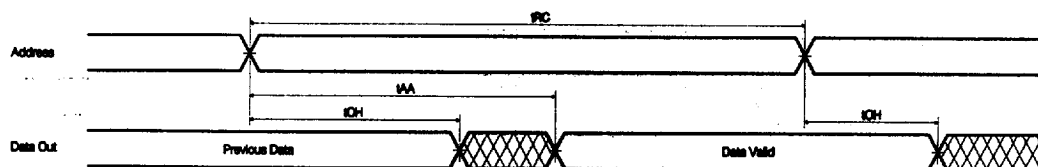
READ CYCLE 1



Note (READ CYCLE):

1. tCHZ and tOHZ are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
2. At any given temperature and voltage condition, tCHZ max. is less than tOLZ min. both for a given device and from device to device.
3. WE is high for read cycle.

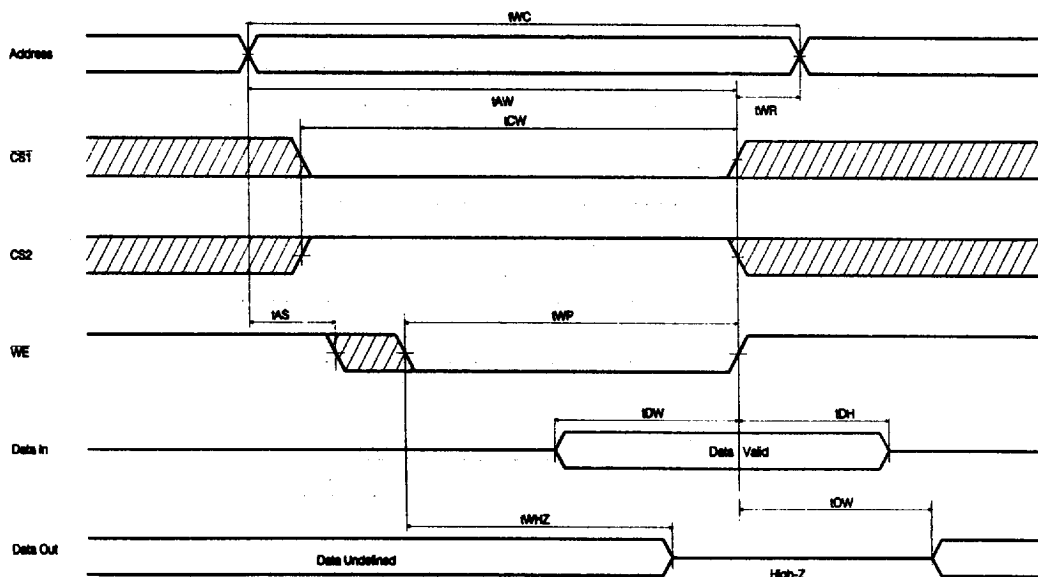
READ CYCLE 2



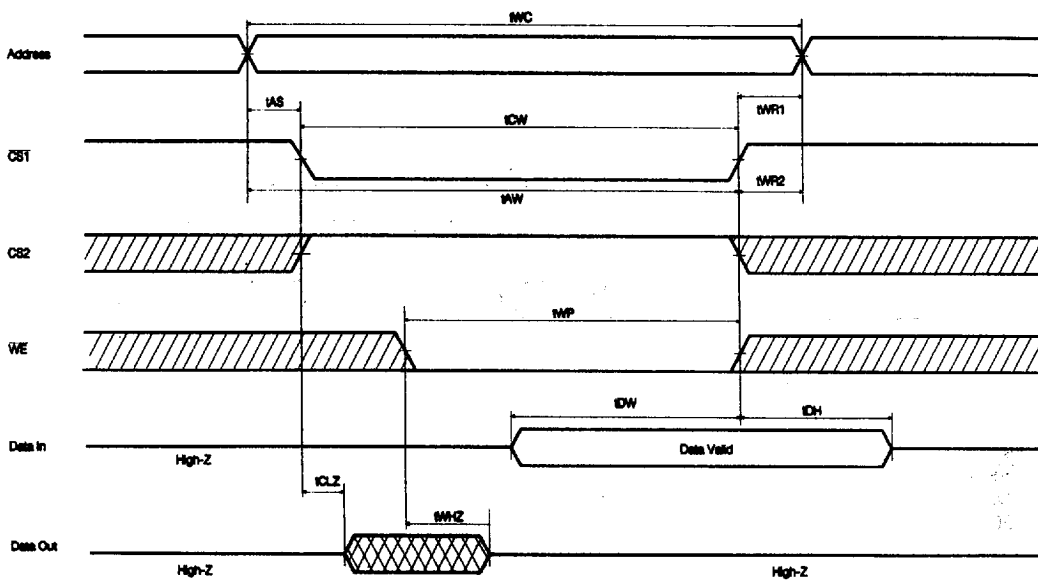
Note(READ CYCLE):

1. WE is high for read cycle.
2. Device is continuously selected $\overline{CS}=V_{IL}$, $CS2=V_{IH}$.
3. $\overline{OE}=V_{IL}$.

WRITE CYCLE 1 ($\overline{WE}$ Controlled)

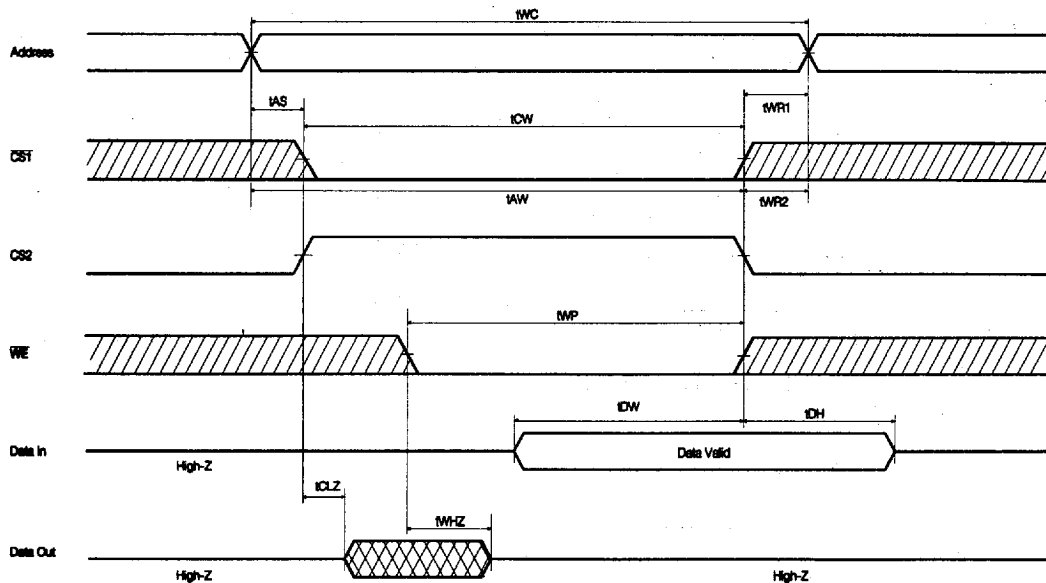


WRITE CYCLE 2 ($\overline{CS1}$ Controlled)



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WRITE CYCLE 3 (CS2 Controlled)



NOTE (WRITE CYCLE):

1. A write occurs during the overlap of a low $\overline{CS1}$ and high $\overline{CS2}$ and a low $\overline{WE}$. A write begins at the latest transition among $\overline{CS1}$ going low, $\overline{CS2}$ going high and $\overline{WE}$ going low: A write ends at the earliest transition among $\overline{CS1}$ going high, $\overline{CS2}$ going low and $\overline{WE}$ going high. t_{WP} is measured from the beginning of write to the end of write.
2. t_{WC} is measured from the later of $\overline{CS1}$ going low or $\overline{CS2}$ going high to end of write.
3. t_{AS} is measured from the address valid to the beginning of write.
4. t_{WR1} is measured from the end of write to the address change. t_{WR1} applied in case a write ends as $\overline{CS1}$, or $\overline{WE}$ going high, t_{WR2} applied in case a write ends at $\overline{CS2}$ going low.
5. If $\overline{OE}$, $\overline{CS2}$ and $\overline{WE}$ are in the read mode during this period, the I/O pins are in the output low-Z state, inputs of opposite phase of the output must not be applied because bus contention can occur.
6. If $\overline{CS1}$ goes low simultaneously with $\overline{WE}$ going low or after $\overline{WE}$ going low, the outputs remain in high impedance state.
7. $DOUT$ is the read data of the new address.
8. When $\overline{CS1}$ is low and $\overline{CS2}$ is high, I/O pins are in the output state. The input signals in the opposite phase leading to the outputs should not be applied.

DATA RETENTION CHARACTERISTICS

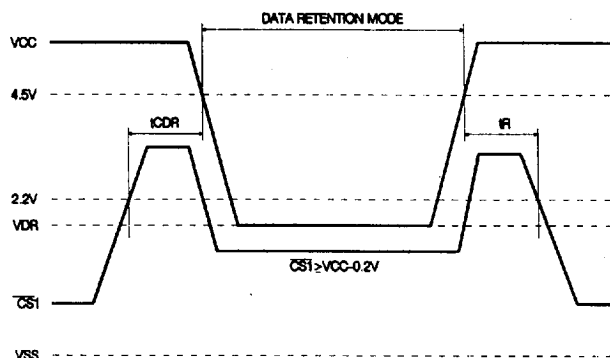
(TA=-40°C to 85°C)

SYMBOL	PARAMETER	TEST CONDITION	POWER	MIN.	TYP.	MAX	UNIT
VDR	VCC for Data Retention	$\overline{CS1} \geq V_{CC}-0.2V$, $CS2 \leq 0.2V$ or $\geq V_{CC}-0.2V$ $V_{SS} \leq V_{IN} \leq V_{CC}$		2.0	-	-	V
ICCDR	Data Retention Current	$V_{CC}=3.0V$, $\overline{CS1} \geq V_{CC}-0.2V$, $CS2 \leq 0.2V$ or $\geq V_{CC}-0.2V$, $V_{SS} \leq V_{IN} \leq V_{CC}$	L	-	1	50	μA
			LL	-	0.5	15	μA
tCDR	Chip Disable to Data Retention Time	See Data Retention Timing Diagram		0	-	-	ns
tR	Operating Recovery Time			tRC ⁽²⁾	-	-	ns

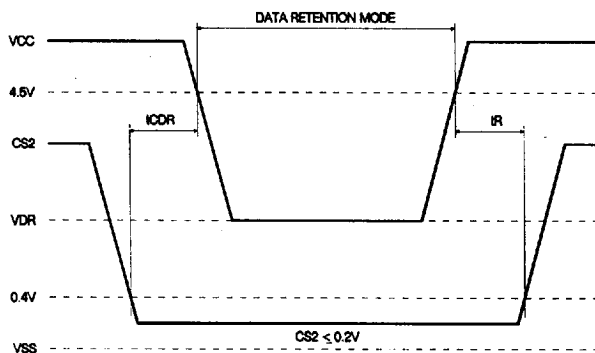
Notes :

1. Typical values are at the condition of TA=25°C.
3. tRC is read cycle time.

DATA RETENTION TIMING DIAGRAM 1

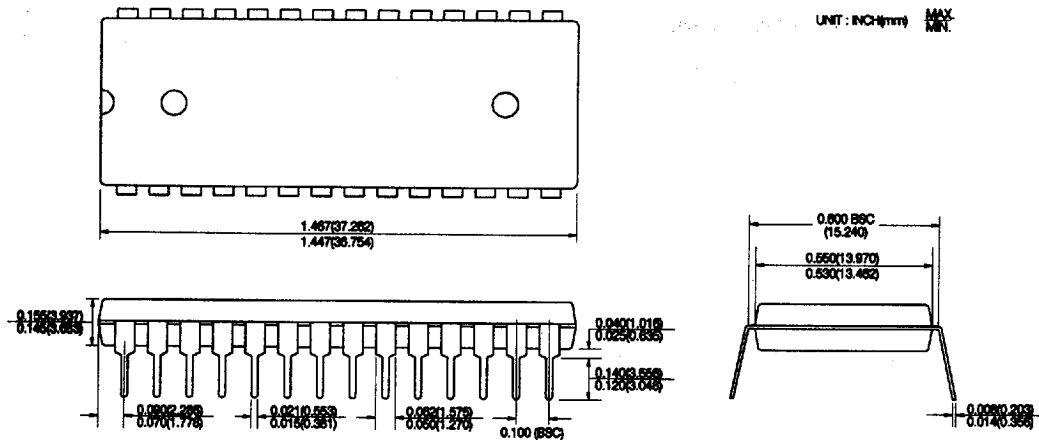


DATA RETENTION TIMING DIAGRAM 2

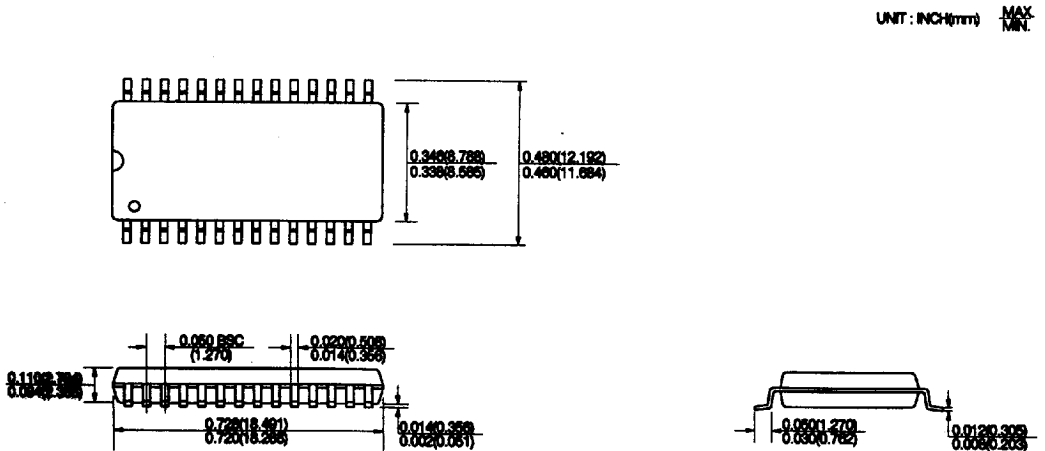


PACKAGE INFORMATION

600 mil 28 pin Dual In-line Package(P)



330mil 28 pin Small Outline Package (J)



ORDERING INFORMATION

PART NO.	SPEED	POWER	PACKAGE
HY6264ALP-I	70/85/100/120	L-part	PDIP
HY6264ALLP-I	70/85/100/120	LL-part	PDIP
HY6264ALJ-I	70/85/100/120	L-part	SOP
HY6264ALLJ-I	70/85/100/120	LL-part	SOP